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TAO FENG; Hong Kong**Assignee: **XINKE INDUSTRY CO., LTD. Hong Kong**
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[Re](#)Published / Filed: **2002-11-06 / 2000-08-09**Application Number: **CN2000000814030**IPC Code: **G11B 5/53; G11B 5/49; G11B 5/48;**ECLA Code: **None**Priority Number: **2000-08-09 WO200000000227**INPADOC **None** [Get Now: Family Legal Status Report](#)

Legal Status:

Designated **CN**

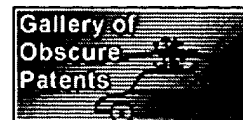
Country:

Family:

PDF	Publication	Pub. Date	Filed	Title
	WO0213189C1	2002-03-14	2000-08-09	BONDING PAD OF SUSPENSION CIRCUIT
	WO0213189A1	2002-02-14	2000-08-09	BONDING PAD OF SUSPENSION CIRCUIT
	US20030058577A1	2003-03-27	2002-11-13	Bonding pad of suspension circuit
	US20020030935A1	2002-03-14	2000-12-18	Bonding pad of suspension circuit
<input checked="" type="checkbox"/>	CN1378685T	2002-11-06	2000-08-09	BONDING PAD OF SUSPENSION CIRCUIT
5 family members shown above				

Other Abstract
Info:

DERABS G2002-315379

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